

SOT811-1

plastic ball grid array package; 256 balls; body 17 x 17 x 1.2 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA256
Package type industry code	BGA256
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	15-4-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	16.8	-	17	17.2	mm
E	package width	16.8	-	17	17.2	mm
A	seated height	[tbd]	-	1.8	1.8	mm
A ₂	package height	1.1	-	1.2	1.35	mm
n ₂	actual quantity of termination	-	-	256	-	



2. Package outline

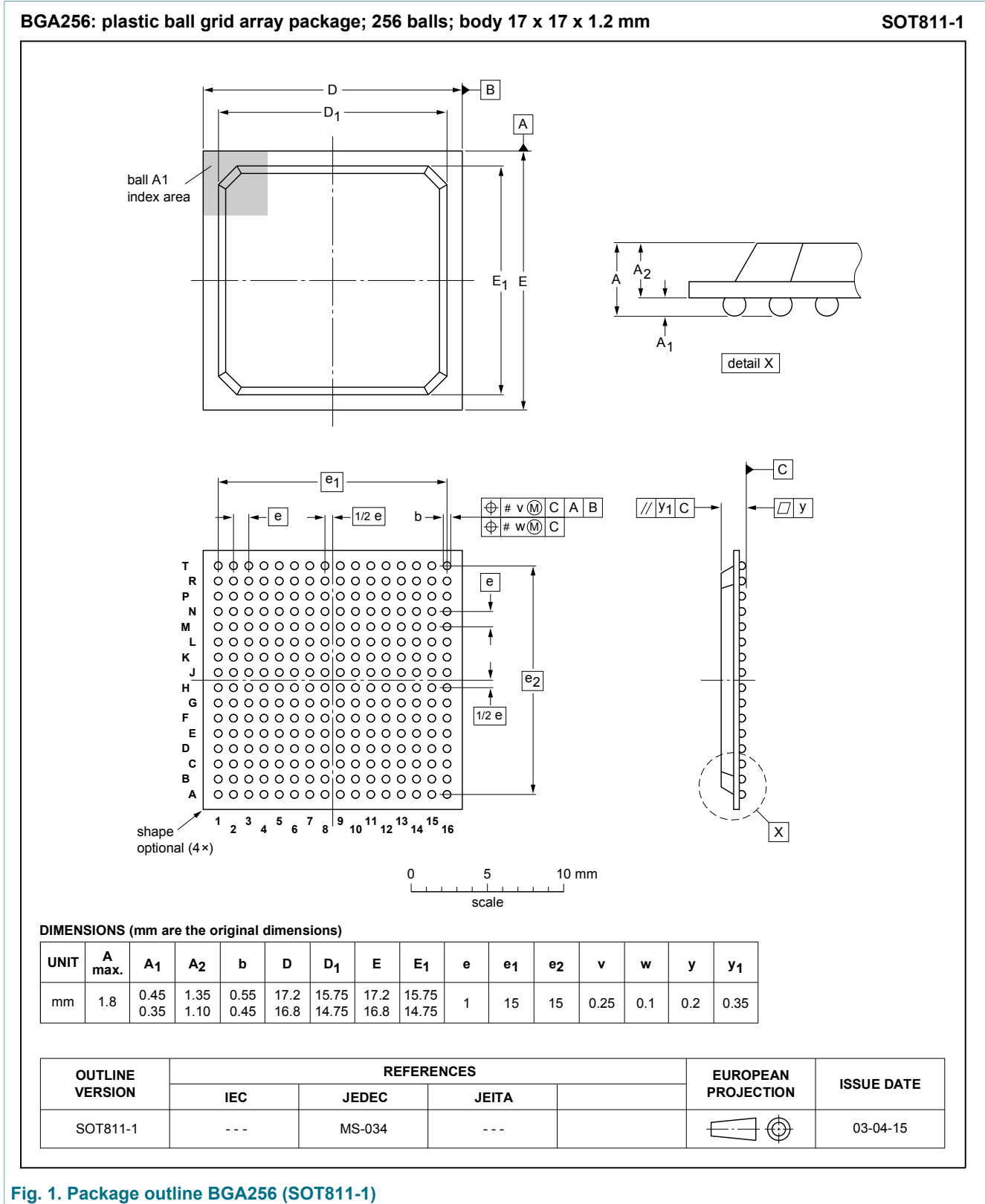
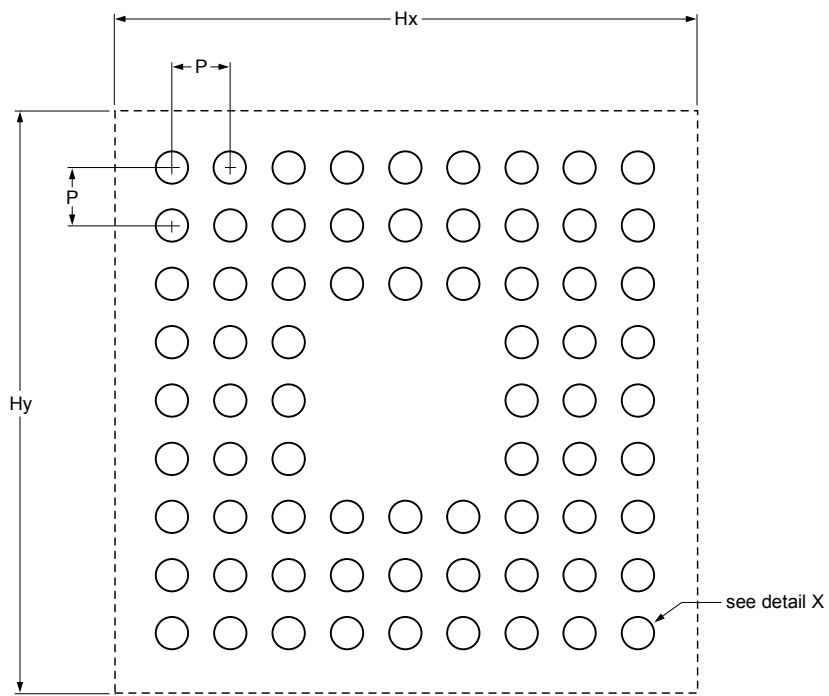


Fig. 1. Package outline BGA256 (SOT811-1)

3. Soldering

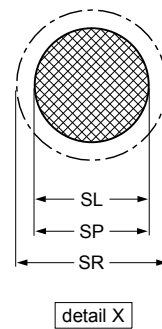
Footprint information for reflow soldering of BGA256 package

SOT811-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste
- occupied area
- _____ solder resist



DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
1.00	0.450	0.450	0.600	17.575	17.575

tot811-1_fr

Fig. 2. Reflow soldering footprint for BGA256 (SOT811-1)

4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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